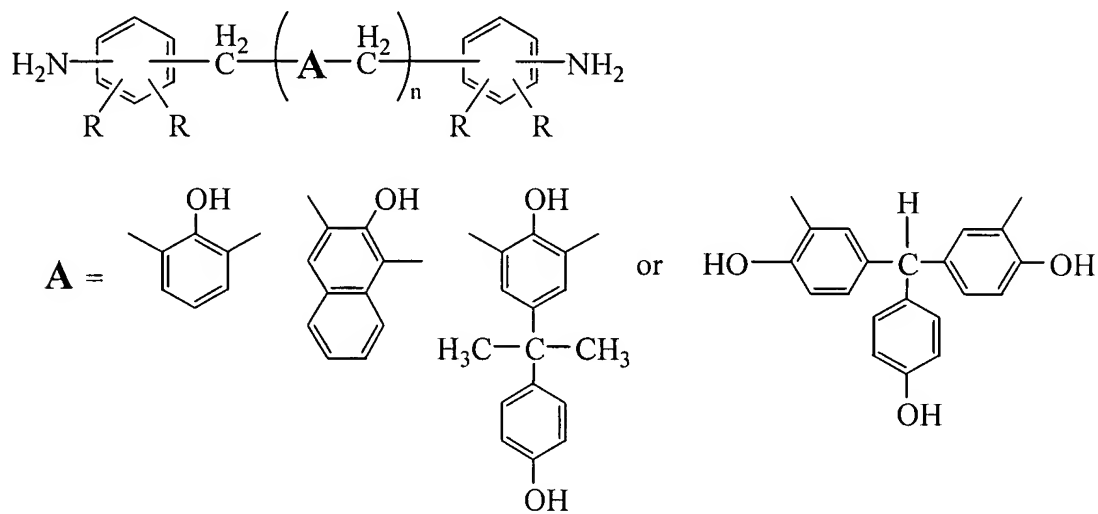


**AMENDED CLAIM SET:**

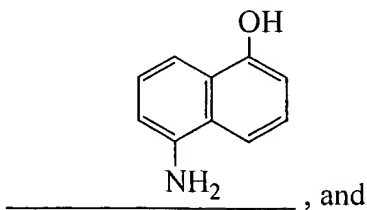
1. (currently amended) A liquid epoxy resin composition comprising
- (A) a liquid epoxy resin,
- (B) an aromatic amine curing agent ~~having a phenolic hydroxyl group in a skeleton~~  
selected from the group consisting of compounds of Formula (1) and Formula (2)

Formula (1)



wherein “n” is an integer of 1 to 5 and “R” is hydrogen, halogen, C<sub>1-8</sub>-alkyl, C<sub>1-8</sub>-alkenyl, C<sub>1-8</sub>-alkynyl, trifluoromethyl, or phenyl and the substituent groups on each aromatic ring may be the same or different

Formula (2)



(C) an inorganic filler.

2. (withdrawn – currently amended) The composition of claim 1, further comprising (D) a silicone-modified resin in the form of a copolymer which is obtained from an alkenyl group-containing epoxy resin or phenolic resin and an organopolysiloxane having the average compositional formula (6):



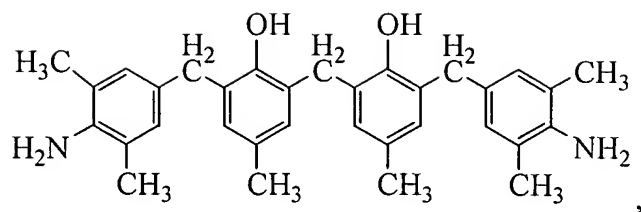
wherein  $\text{R}^5$  is a substituted or unsubstituted monovalent hydrocarbon group, "a" is a number of 0.01 to 0.1, "b" is a number of 1.8 to 2.2, and  $1.81 \leq a+b \leq 2.3$ , said organopolysiloxane containing per molecule 20 to 400 silicon atoms and 1 to 5 hydrogen atoms each directly attached to a silicon atom (i.e., SiH groups), by effecting addition reaction between alkenyl groups and SiH groups.

3. (original) A semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state.

4. (original) A flip chip type semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state as an underfill.

5. (currently amended) The liquid epoxy resin composition of claim 1, wherein component (A) is ~~bisphenol F-type~~ a bisphenol F epoxy resin, ~~component (B) is tetraethyldiaminophenylmethane~~, and component (C) is spherical silica.

6. (withdrawn – currently amended) The liquid epoxy resin composition of claim 5, further comprising (B) a diamine of the formula



phenyl glycidyl ether,  $\gamma$ -glycidoxypolytrimethoxysilane, and a copolymer addition reaction product of

